3.5x2.8mm SURFACE MOUNT LED LAMP

Part Number: AA3528SES/J4

Super Bright Orange

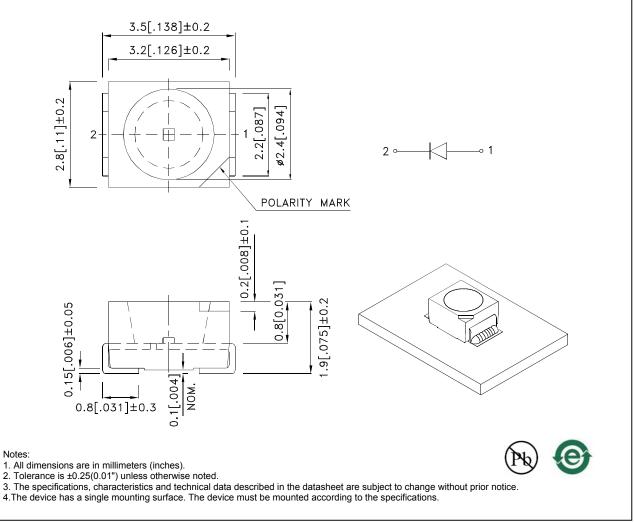
Features

- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Orange source color devices are made with AlGaInP Light Emitting Diode.

Package Dimensions

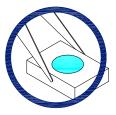


SPEC NO: DSAL3956 APPROVED: WYNEC REV NO: V.2A CHECKED: Allen Liu DATE: AUG/31/2012 DRAWN: D.M.Su PAGE: 1 OF 6 ERP: 1201007397

Handling Precautions

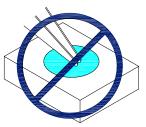
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

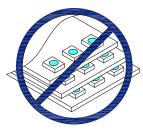


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

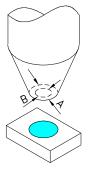




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

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Selection Guide

Selection Guide					
Part No.	Dice	Dice Lens Type @ 20mA		/ - -	Viewing Angle [1]
			Min.	Тур.	201/2
AA3528SES/J4	Super Bright Orange (AlGaInP)	Water Clear	2300	2800	120°
			*700	*850	

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%. *Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	611		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	605		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	17		nm	I⊧=20mA
С	Capacitance	Super Bright Orange	27		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Super Bright Orange	2.2	2.8	V	l⊧=20mA
IR	Reverse Current	Super Bright Orange		10	uA	VR=5V

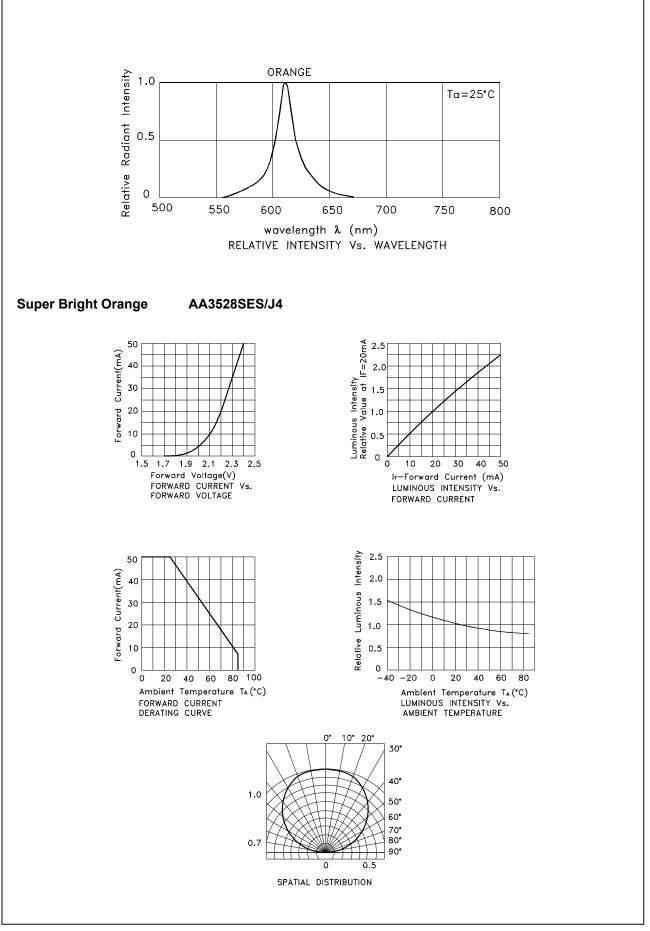
Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units	
Power dissipation	140	mW	
DC Forward Current	50	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

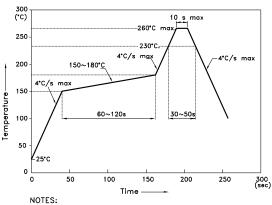
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



AA3528SES/J4

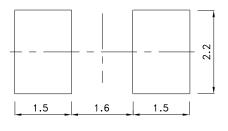
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

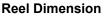
Reflow Soldering Profile For Lead-free SMT Process.

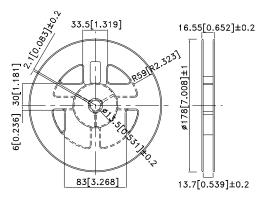


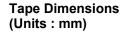
NOTES: 1.We recommend the reflow temperature $245^{\circ}C(+/-5^{\circ}C)$. The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

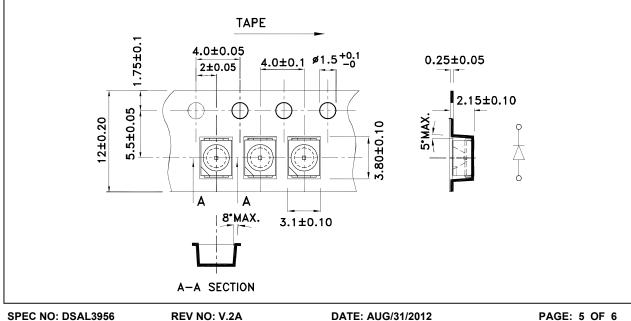












SPEC NO: DSAL3956 APPROVED: WYNEC

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PAGE: 5 OF 6 ERP: 1201007397

